

# P60C081\_SDS

SmartMX2 Family P60C081y

Rev. 3.0 — 27 September 2016

Public product data sheet  
COMPANY PUBLIC

## 1 General description

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The P60C081 contact interface secure microcontroller is part of the most recent P60-Step-Up! family generation and builds on the IntegralSecurity architecture. It delivers unprecedented security, extended memory footprint, and highest performance across all typical up-to-date requested fast transaction cases in Payment and eGov. Furthermore, it comes with certified crypto library modules and can be ordered in various advanced package options for contact operation.

## 2 Features and benefits

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### 2.1 Key features

- User EEPROM: up to 80 KB
- User ROM: 384 KB
- User RAM: up to 8128 Bytes
- Contact Interface Type according to ISO/IEC 7816
- Hardware-based Physically Unclonable Function (PUF) implemented: provides strong protection for secret keys and data
- SmartICE Development tool chain with true bond-out chip and Softmasking Device allows faster time to market

### 2.2 Hardware features

- Economic and resilient ROM/EEPROM design
  - data retention time: 25 years minimum
  - endurance: 500000 cycles
  - versatile EEPROM programming: 1 B to 128 B at a time
- SmartMX2 CPU with orthogonal instruction set offering 32-/24-/16-/8-bit instructions optimized for secured and low-power smart card applications
- Dedicated high-performance secure coprocessor FAME2 for Public Key Infrastructure (PKI) cryptography (RSA, ECC)
- High-performance secured hardware support for symmetric block cipher algorithms:
  - Dual/triple DES and AES, all key lengths
  - Dedicated hardware support for SEED and OSCCA algorithms, multiple key and data register sets for parallel data/key loading and calculation
- True Random Number Generator (compliant to AIS-31)
- 16-bit and 32-bit CRC coprocessor supporting fast memory-verify functionality Memory Management Unit (MMU):
  - 16 segment cache entries and performance improvements



- Supporting integral concept for secure code fetch and execution
- Copy Machine offering data transfer between all Special Function Registers and all Memory instances without CPU interaction
- Watchdog Timer supporting secure code execution, Time Stamp Counter, Real Time Clock
- Continuous operation from 1.62 V up to 5.5 V
- Operating ambient temperature from -25 °C to +85 °C

### 2.3 Security features

- Outstanding Glue Logic chip layout based on the IntegralSecurity™ architecture concept:
  - Most efficient and proven protection against reverse engineering
  - Impossible to recognize logical blocks by means of optical inspection
- Advanced security sensors on clock, temperature, supply voltage, light, and single fault injection
- Active and dynamic shielding
- Advanced memory security (encryption and physical measures) for RAM, EEPROM and ROM
- OS controlled access restriction mechanism to peripherals in user mode
- Programmable card disable feature
- Physically Unclonable Function hardware support to secure keys against new attack scenarios
- Metal layer design for highest attack resilience
- No general standard core or re-used hard macro applied
- No use of ROM-based micro code
- Certificates and approvals; Common Criteria up to EAL6+, EMVCo

## 2.4 Additional features

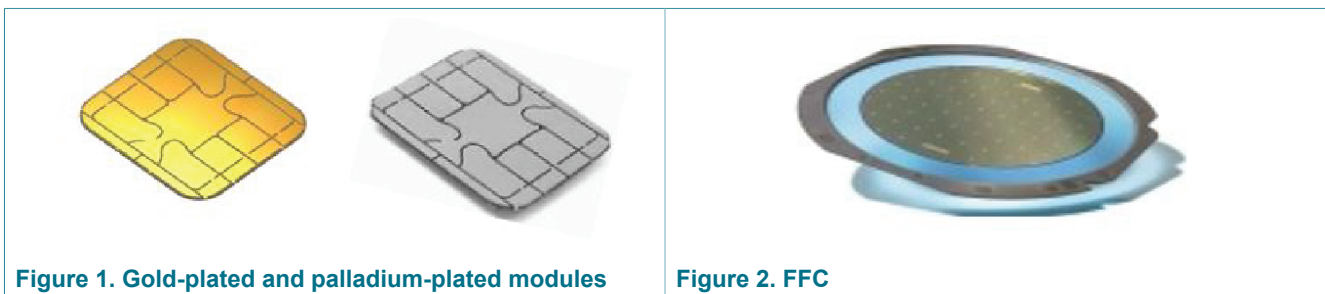
- CC security certified crypto library as a commercial option:
  - Consists of easy to use APIs for all algorithms, allows for dynamic use of memory resources
  - Safeguards secure operation in contact mode
  - Includes state-of-the-art and future-proof built-in security features to avoid power (SPA/DPA), timing and fault attacks (DFA)
  - Every module is available separately
  - RSA encryption and decryption (256 ... 4096 bit key length)
  - RSA signature generation and verification (256 ... 4096 bit key length)
  - RSA key generation (plain and CRT format, 256 ... 4096 bit key length)
  - ECC over GF(p) signature generation and verification (128 ... 576 bit key length)
  - ECC over GF(p) key generation and Diffie-Hellman key exchange (128 ... 576 bit key length)
  - ECC over GF(p) full point addition
  - SHA-1, SHA-224, SHA-256, SHA-384 and SHA-512 hash computation
  - DES encryption, decryption and MAC (S-DES and T-DES with 2 & 3 keys)
  - AES encryption, decryption and MAC calculation (128, 192, 256 bit key length)
  - Pseudo Random number generation based on a deterministic random number generator, generator of type K4
- Service on batch, wafer or die-individual security data, secure transport keys:
  - Various EEPROM initialization options available to facilitate customer's personalization
  - Comprehensive offer on NXP Trust Provisioning service options

## 3 Development tools

- Development tool chain, based on approved suppliers Keil and Ashling:
  - Well-perceived  $\mu$ Vision user interface
  - Fast and efficient compiler, loader and timing-accurate simulator software
  - High-performance emulation hardware "SmartICE series"
  - Close-to-product emulation safeguarded via a true bond-out controller
- Tutorial Libraries with dedicated customer application support via local NXP Field Application Engineers

## 4 Packages and applications

- Rich selection of contact chip modules on tape:
  - Approved selection of gold-plated and palladium-plated chip modules ([Figure 1](#))
  - Benchmark in robust molded modules
  - Wafer deliveries in different thicknesses on Film Frame Carrier (FFC), [Figure 2](#)
- Full coverage of today’s performance needs for:
  - Payment and eGov applications
  - Transport & access management
  - Device authentication



## 5 Revision history

Table 1. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
P60C081_SDS v.3	20160927	Product data sheet	-	-

## 6 Legal information

### 6.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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## Contents

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<b>1</b>	<b>General description .....</b>	<b>1</b>
<b>2</b>	<b>Features and benefits .....</b>	<b>1</b>
2.1	Key features .....	1
2.2	Hardware features .....	1
2.3	Security features .....	2
2.4	Additional features .....	3
<b>3</b>	<b>Development tools .....</b>	<b>3</b>
<b>4</b>	<b>Packages and applications .....</b>	<b>4</b>
<b>5</b>	<b>Revision history .....</b>	<b>4</b>
<b>6</b>	<b>Legal information .....</b>	<b>5</b>

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For sales office addresses, please send an email to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)

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